

Oral session

Keynote/Invited	Presentation NO	Presentation date	Time to start	Time to finish	Account: First name	Account: Middle name	Account: FAMILY NAME	Account: Affiliation	Abstract title
Chairpersons: Chris CORDONIER									
	C-10-O27-001	27 Sep.	10:30	10:50	Kiyoshi		SAKURAI	Kanto Gakuin University	Corrosion Resistance and Surface Analysis of Formed Inhibitor Film on Nickel
	C-10-O27-002	27 Sep.	10:50	11:10	Susumu		TAKEMURA	College of Engineering, Kanto Gakuin University	Photoluminescence Study of Nanostructured Aluminum Surface Coated by Polythiophene Film
	C-10-O27-003	27 Sep.	11:10	11:30	Michinori		TAKAGI	YOSHINO DENKA KOGYO INC.	Dispersion method of SiC for electroless Ni-P Composite plating
	C-10-O27-004	27 Sep.	11:30	11:50	Han		ZUILHOF	Wageningen University	Photochemical Grafting and Patterning of Organic Monolayers onto Indium Tin Oxide Substrates
Lunch 27 Sep. 11:50 13:30									
Chairpersons: Hitoshi KATO									
	C-10-O27-005	27 Sep.	13:30	13:50	Kozo		OBARA	Kagoshima University	Condensation Processes of Long Lifetime Zn Excimers produced by Ion-recombination Processes
	C-10-O27-006	27 Sep.	13:50	14:10	Jin		KAWAKITA	National Institute for Materials Science	Photo-induced action upon fast chemical formation of highly conductive polymer with metal shell structure
Invited	C-10-I27-007	27 Sep.	14:10	14:50	Yong		CHOI	Department of Materials Science and Engineering, Dankook University	In-situ Analysis of Interface Stability of Electro-formed Nano-sized Copper-Nickel Multi-layers by Using Small Angle Neutron Scattering
Coffee Break 27 Sep. 14:50 15:15									
Chairpersons: Hitoshi KATO									
Invited	C-10-I27-008	27 Sep.	15:15	15:55	JINN	P.	CHU	National Taiwan University of Science and Technology	Enhanced Thermal Stability of Copper Alloy Films for Barrierless Metallization
Chairpersons: Yong CHOI									
	C-10-O28-001	28 Sep.	9:00	9:20	Kazunori		MATSUI	Kanto Gakuin University	Spectroscopic Studies of Organic Molecules Embedded in Anodic Porous Alumina
	C-10-O28-002	28 Sep.	9:20	9:40	Chris	E. J.	CORDONIER	Kanto Gakuin University	High Resolution Direct Photo-patterning for Build-up Micro-circuit Fabrication
	C-10-O28-003	28 Sep.	9:40	10:00	Masayuki		OKOSHI	National Defense Academy	Photochemical Surface and Interface Modifications of Aluminum Thin Films on Silica Glass by F2 Laser for Micro-Patterning
	C-10-O28-004	28 Sep.	10:00	10:20	Hitoshi		KATO	Kanto Gakuin University	Nanopattern Formation of Conducting Polymer Polyaniline on Nanostructured Aluminum Surfaces and Nano-Contact Transcription of the Nano-Pattern to Si Wafer
Coffee Break 28 Sep. 10:20 10:30									
Chairpersons: Hideo HONMA									
Invited	C-10-I28-005	28 Sep.	10:30	11:10	Mark		BACHMAN	University of California Irvine	Electrochemical Process Integration for Non-Silicon Microdevices
Break Time 28 Sep. 11:10 11:20									
Invited	C-10-I28-006	28 Sep.	11:20	12:00	G.-P.		LI	University of California Irvine	Convergence of MEMS and Packaging Technology
Lunch 28 Sep. 12:00 13:30									
Chairpersons: Mark BACHMAN									
	C-10-O28-007	28 Sep.	13:30	13:50	Kotoku		INOUE	KOTO Electric Co., LTD.	Thick Conductive Layer Formation on Glass Substrate with a Wet Process
	C-10-O28-008	28 Sep.	13:50	14:10	Satoshi		KAWASHIMA	Meltex Inc.	Electroless plating process on Glass.
	C-10-O28-009	28 Sep.	14:10	14:30	Win	Maw	SOE	PI R&D CO.,Ltd.	Electroless depositable Polyimide Ink used for crystalline Si Solar cell and new surface treatment method for polyimide and Si substrate
	C-10-O28-010	28 Sep.	14:30	14:50	SOJIRO		KIRIHARA	ERG co.,LTD	Stress Control in High-Speed Plating with an Acetic Acid Containing Nickel-Sulfamate Bath
Coffee Break 28 Sep. 14:50 15:00									
Chairpersons: Gregory KIM									
	C-10-O28-011	28 Sep.	15:15	15:35	Hiroaki		SUZUKI	OKUNO CHEMICAL INDUSTRIES Co.,Ltd	The electroless Ni-P plating film for Flexible Printed Circuit Boards
	C-10-O28-012	28 Sep.	15:35	15:55	Yaichiro		NAKAMARU	EBARA-UDYLITE CO.,LTD.	Improvement of Adhesion Strength between Polyimide Film and Plated Film by Hydrofluoric Acid Treatment
	C-10-O28-013	28 Sep.	15:55	16:15	Kumiko		ISHIKAWA	Ebara-Udylite Co.,Ltd.	Investigation of Palladium Removal Process for Fine Circuit Patterns

Poster Session

Presentation NO	Presentation date	Time to start	Time to finish	Account: First name	Account: Middle name	Account: FAMILY NAME	Account: Affiliation	Abstract title
C-10-P25-001	25 Sep.	18:00	20:00	Hiroyuki		SESHITA	Kanto Gakuin University	Attempt to Organic-inorganic Hybrid Architectures on Copper Surface in Aqueous Solution of Formamide and Aniline
C-10-P25-002	25 Sep.	18:00	20:00	Yuta		AWAIHARA	National Defense Academy	Surface Modification of Iron Thin Films by F2 Laser for Micro-Patterning
C-10-P25-003	25 Sep.	18:00	20:00	Yoshiaki		OUYA	Kanto Gakuin University	Effect of Buffer Agent on the Nickel Deposition in Citric Acid Bath
C-10-P25-004	25 Sep.	18:00	20:00	Yasushi		SASAKI	Faculty of Engineering, Kanto Gakuin University	Characteristics of nickel hydroxide electrode prepared from electrochemical impregnation
C-10-P25-005	25 Sep.	18:00	20:00	Futoshi		MATSUMOTO	Kanagawa University	The Wear Resistance Property of Cu/Ni Multilayer Films Prepared by
C-10-P25-006	25 Sep.	18:00	20:00	Futoshi		MATSUMOTO	Kanagawa University	Application of Ordered Intermetallic Phases to Electrocatalysis
C-10-P25-007	25 Sep.	18:00	20:00	Kaori		URASAKI	Tokyo Metropolitan Industrial Technology Research Institute	Fundamental study on application of the low environmental load nickel electroplating used citric acid to plating of electronic components
C-10-P25-008	25 Sep.	18:00	20:00	hidetoshi		OGURA	Okuno Chemical Ind. Co., Ltd.	Acid Copper Plating Additive for Via-Filling Applicable at Wide Range of Current density
C-10-P25-009	25 Sep.	18:00	20:00	Tomo		MORIGUCHI	Okuno Chemical Industries Co.,LTD	Influence of Electroless Copper Additives to Isolated Circuit on Selective Deposition Ability
C-10-P25-010	25 Sep.	18:00	20:00	Hitoshi		KATO	Kanto Gakuin University	Arrangement of Carbon Nanotubes on Nanostructured Aluminum Surfaces and Nano-Contact Transcription of the Nano-Pattern to a Silicon Wafer
C-10-P25-011	25 Sep.	18:00	20:00	Yohei		WATANABE	College of Engineering, Kanto Gakuin University	Nanoscale Pattern Formation of Nano-Graphite on Nanostructured Aluminum Surface by Carbon Drawing
C-10-P25-012	25 Sep.	18:00	20:00	Yohei		WATANABE	College of Engineering, Kanto Gakuin University	Dynamic Force Microscopy and Raman Spectroscopy Studies of Carbon Drawn Nano-Graphite Patterns on Nanostructured Al Surface and on Si Wafer
C-10-P25-013	25 Sep.	18:00	20:00	Atsuro		ISHII	Kanto Gakuin University	Photoluminescence characterization of dye molecule filling highly-oriented pillared structure formed on Al surface by chemical and electrochemical multi-process
C-10-P25-014	25 Sep.	18:00	20:00	Susumu		TAKEMURA	College of Engineering, Kanto Gakuin University	Photoluminescence Characterization of Polythiophene Incorporated with Metallophthalocyanine Molecules
C-10-P25-015	25 Sep.	18:00	20:00	Ken		OKUBO	Kanto Gakuin University	Synthesis and Evaluation of Terminal-modified Polyethylene Glycol
C-10-P25-016	25 Sep.	18:00	20:00	Kunihito		BABA	Japan Surface Treatment Institute co.,Ltd.	Application of a New Aluminum Etching Process
C-10-P25-017	25 Sep.	18:00	20:00	Sardarbek	Bakhadirovich	KHUDAYBERGAN	National University of Uzbekistan named after Mirzo Ulugbek	Investigation of the influence surface with hydrogen passivation links to diamond-like silicon clusters
C-10-P25-018	25 Sep.	18:00	20:00	Ichiro		KOIWA	Kanto Gakuin University	Magnetic Force-Based Microarray Chip for Medical Care Prepared by Plating Method
C-10-P25-019	25 Sep.	18:00	20:00	NOBUAKI		WATANABE	Kanto Gakuin University	Characterization of Zn-Al2O3 Composite Films Prepared by Electrochemical Reaction
C-10-P25-020	25 Sep.	18:00	20:00	Tatsunosuke		NAKADA	Kanto Gakuin University	Application of the Electroless Plating to Metallize Electrodes of Chip Components
C-10-P25-021	25 Sep.	18:00	20:00	Junki		OSHIKIRI	Kanto Gakuin University	Effect of Complexing Agents of Electroless Ni-P Plating Bath on Metallization to SiN Substrate
C-10-P25-022	25 Sep.	18:00	20:00	takatoshi		HARA	Kanto Gakuin University	Effect of Molybdenum Codeposition on Cu-Mo Alloy Films
C-10-P25-023	25 Sep.	18:00	20:00	Takahiro		KAGAMI	Kanto Gakuin University	Direct plating on the Glass Substrate Using Photo-Sol